



AN10343_1

MicroPak soldering information

Rev. 01 — 30 March 2005

Application note

Document information

Info	Content
Keywords	MicroPak, footprint, BGA
Abstract	The recommended solder land pattern for mounting the MicroPak package

Revision history

Rev	Date	Description
01	20050330	MicroPak soldering information

1. Introduction

This application note is to describe mounting methods of MicroPak™ packages.

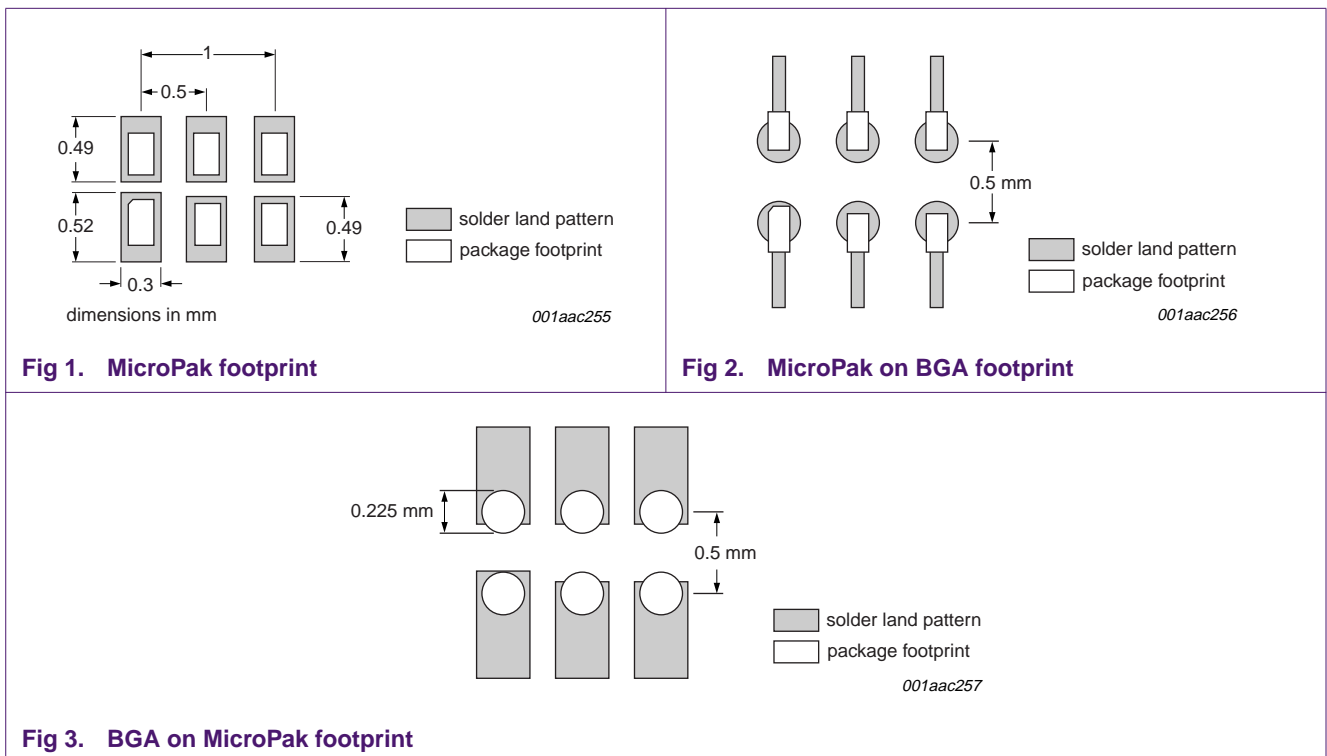
- MicroPak footprint
- MicroPak on BGA footprint
- BGA on MicroPak footprint

2. MicroPak soldering information

The recommended solder land pattern for mounting the MicroPak XSON6 (SOT886) package is shown in [Figure 1](#). Use of this pattern will result in a very good electrical and mechanical connection, which can also be inspected and tested for continuity. Use of the land grid array package eliminates the co-planarity issues of leaded and BGA type devices.

The 6-pad MicroPak package available from Philips Semiconductors is also alternate sourced by Fairchild Semiconductor. While the footprint for the Texas Instruments BGA package is physically smaller, the MicroPak will very easily fit on the same footprint. [Figure 2](#) shows the solder land pattern recommended for the BGA package and how the MicroPak footprint will fit.

Placing the BGA package on the MicroPak footprint would not be recommended. As can be seen in [Figure 3](#), the larger land pattern for the MicroPak may cause solder starvation due to the limited amount of solder in the solder ball of the package. Solder paste would help however, mechanical contact is limited. This is true for the larger Pb free BGA balls, even less mechanical contact is achieved with the smaller PbSn BGA balls.



3. Package outline

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

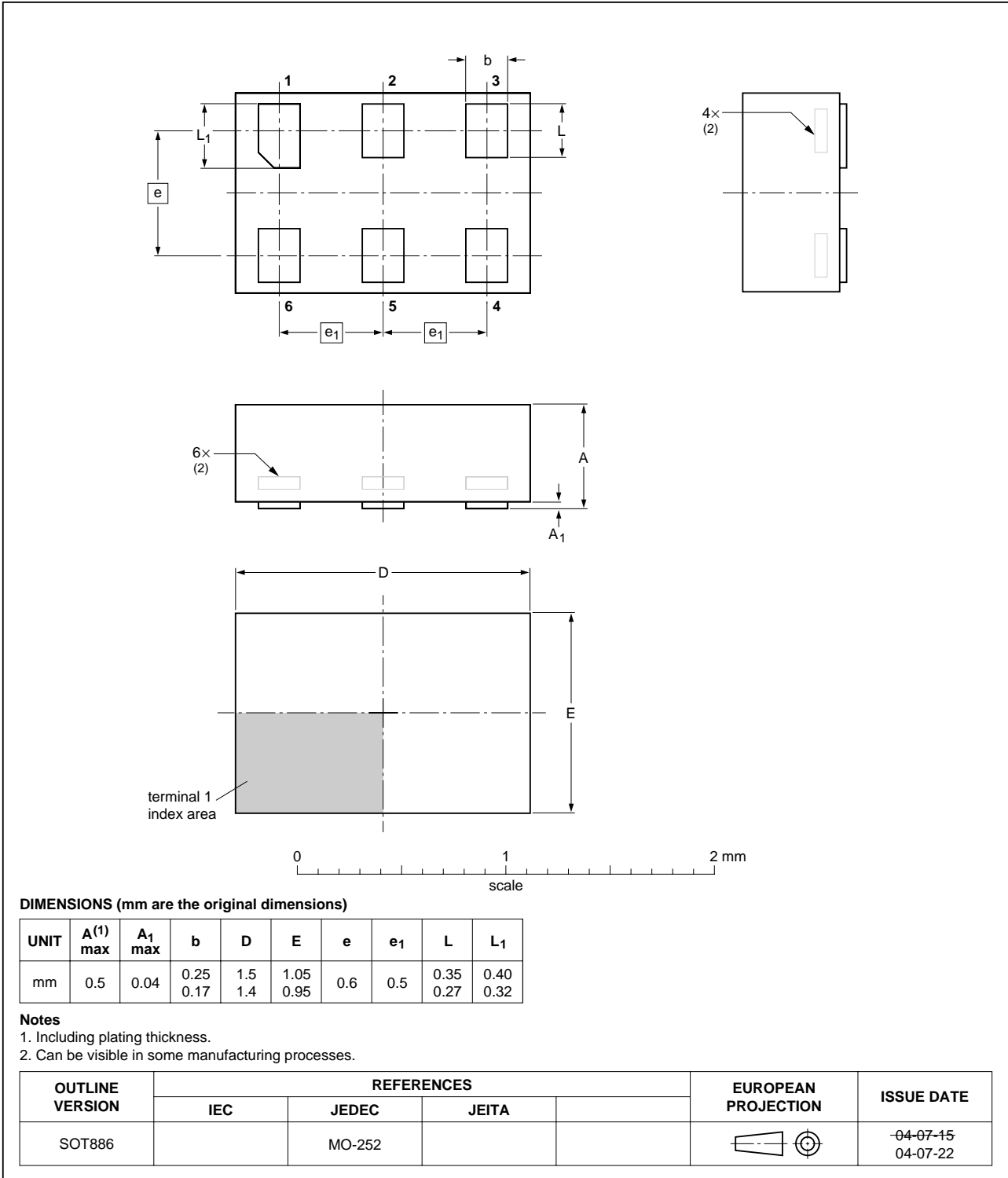


Fig 4. Package outline SOT886 (XSON6)

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